

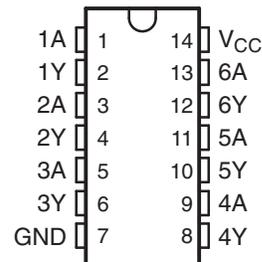
## RAD-TOLERANT CLASS V, HEX SCHMITT-TRIGGER INVERTER

 Check for Samples: [SN54AC14-SP](#)

### FEATURES

- 2-V to 6-V  $V_{CC}$  Operation
- Inputs Accept Voltages to 6 V
- Max tpd of 9.5 ns at 5 V
- Rad-Tolerant: 50 kRad(Si) TID <sup>(1)</sup>
  - TID Dose Rate < 2mRad/sec
- QML-V Qualified, SMD 5962-87624

(1) Radiation tolerance is a typical value based upon initial device qualification. Radiation Lot Acceptance Testing is available - contact factory for details.

**J OR W PACKAGE  
(TOP VIEW)**


### DESCRIPTION/ORDERING INFORMATION

These Schmitt-trigger devices contain six independent inverters. They perform the Boolean function  $Y = \bar{A}$ . Because of the Schmitt action, they have different input threshold levels for positive-going ( $V_{T+}$ ) and for negative-going ( $V_{T-}$ ) signals.

These circuits are temperature compensated and can be triggered from the slowest of input ramps and still give clean, jitter-free output signals. They also have a greater noise margin than conventional inverters.

#### ORDERING INFORMATION<sup>(1)</sup>

$T_A$	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	CDIP – J	Tube	5962-8762402VCA	5962-8762402VCA
	CFP – W	Tube	5962-8762402VDA	5962-8762402VDA

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).
- (2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

#### FUNCTION TABLE (EACH INVERTER)

INPUT A	OUTPUT Y
H	L
L	H

#### LOGIC DIAGRAM, EACH INVERTER (POSITIVE LOGIC)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	7	V
$V_I$	Input voltage range <sup>(2)</sup>	-0.5	$V_{CC} + 0.5$	V
$V_O$	Output voltage range <sup>(2)</sup>	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$ or $V_I > V_{CC}$		±20 mA
$I_{OK}$	Output clamp current	$V_O < 0$		±20 mA
$I_O$	Continuous output current	$V_O = 0$ to $V_{CC}$		±50 mA
Continuous current through $V_{CC}$ or GND				±200 mA
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded provided the input and output current ratings are observed.

**RECOMMENDED OPERATING CONDITIONS<sup>(1)</sup>**

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	2	6	V
$V_I$	Input voltage	0	$V_{CC}$	V
$V_O$	Output voltage	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 3$ V	-12	mA
		$V_{CC} = 4.5$ V	-24	
		$V_{CC} = 5.5$ V	-24	
$I_{OL}$	Low-level output current	$V_{CC} = 3$ V	12	mA
		$V_{CC} = 4.5$ V	24	
		$V_{CC} = 5.5$ V	24	
$T_A$	Operating free-air temperature	-55	125	°C

- (1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C		T <sub>A</sub> = -55°C TO 125°C		UNIT
			MIN	MAX	MIN	MAX	
V <sub>T+</sub> Positive-going threshold		3 V		2.3		2.3	V
		4.5 V		3.2		3.2	
		5.5 V		3.9		3.9	
V <sub>T-</sub> Negative-going threshold		3 V	0.5		0.5		V
		4.5 V	0.9		0.9		
		5.5 V	1.1		1.1		
ΔV <sub>T</sub> Hysteresis (V <sub>T+</sub> – V <sub>T-</sub> )		3 V	0.3	1.3	0.3	1.3	V
		4.5 V	0.4	1.4	0.4	1.4	
		5.5 V	0.5	1.6	0.5	1.6	
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	3 V		2.9		2.9	V
		4.5 V		4.4		4.4	
		5.5 V		5.4		5.4	
	I <sub>OH</sub> = -12 mA	3 V		2.56		2.4	
		4.5 V		3.86		3.7	
I <sub>OH</sub> = -24 mA	5.5 V		4.86		4.7		
I <sub>OH</sub> = -50 mA <sup>(1)</sup>	5.5 V				3.85		
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	3 V		0.1		0.1	V
		4.5 V		0.1		0.1	
		5.5 V		0.1		0.1	
	I <sub>OL</sub> = 12 mA	3 V		0.5		0.5	
		4.5 V		0.5		0.5	
	I <sub>OL</sub> = 24 mA	5.5 V		0.5		0.5	
I <sub>OL</sub> = 50 mA <sup>(1)</sup>	5.5 V				1.65		
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V		±0.1		±1	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V		4		80	μA
I <sub>CCt</sub>	V <sub>I</sub> = V <sub>CC</sub> /2 V One input at V <sub>I</sub> , other input at V <sub>CC</sub> or GND <sup>(2)</sup>	5.5 V		7.5		7.5	mA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		8		8	pF

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

 (2) V<sub>I</sub> is incremented in 0.1-V steps to 3.7 V.

### SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range,  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ ,  $C_L = 50\text{ pF}$  (unless otherwise noted)  
(see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			$T_A = -55^\circ\text{C TO } 125^\circ\text{C}$		UNIT
			MIN	TYP	MAX	MIN	MAX	
$t_{PLH}$	A	Y	1.5	6	13.5	1	16	ns
$t_{PHL}$			1.5	6	11.5	1	14	

### SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ ,  $C_L = 50\text{ pF}$  (unless otherwise noted)  
(see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			$T_A = -55^\circ\text{C TO } 125^\circ\text{C}$		UNIT
			MIN	TYP	MAX	MIN	MAX	
$t_{PLH}$	A	Y	1.5	5	10	1.5	12	ns
$t_{PHL}$			1.5	5	8.5	1.5	10	

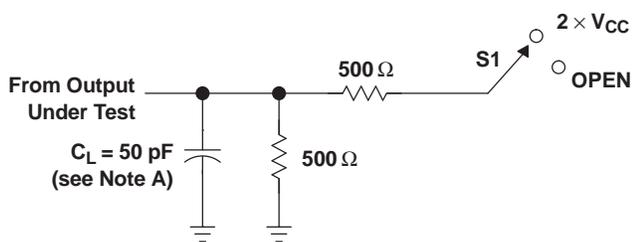
### OPERATING CHARACTERISTICS

$V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

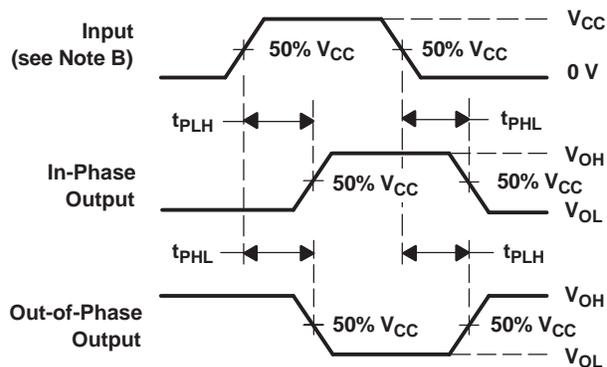
PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance	$C_L = 50\text{ pF}$ , $f = 1\text{ MHz}$	25	pF

PARAMETER MEASUREMENT INFORMATION

TEST	S1
$t_{PLH}/t_{PHL}$	Open



LOAD CIRCUIT



VOLTAGE WAVEFORMS

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .  
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

## REVISION HISTORY

Changes from Revision A (March, 2010) to Revision B	Page
• Added $I_{CCT}$ parameter to Electrical Characteristics .....	3

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8762401VCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401VC A SNV54AC14J	<a href="#">Samples</a>
5962-8762401VDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401VD A SNV54AC14W	<a href="#">Samples</a>
5962-8762402VCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762402VC A SNV54AC14J	<a href="#">Samples</a>
5962-8762402VDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762402VD A SNV54AC14W	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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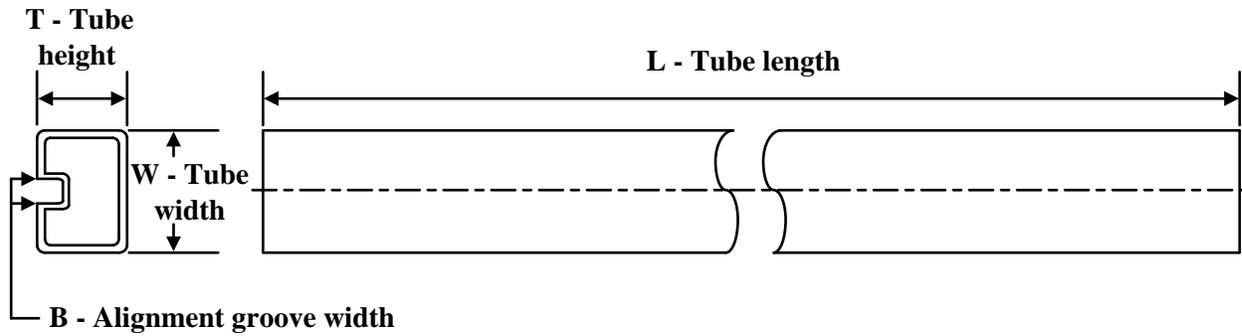
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**OTHER QUALIFIED VERSIONS OF SN54AC14-SP :**

- Catalog : [SN54AC14](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

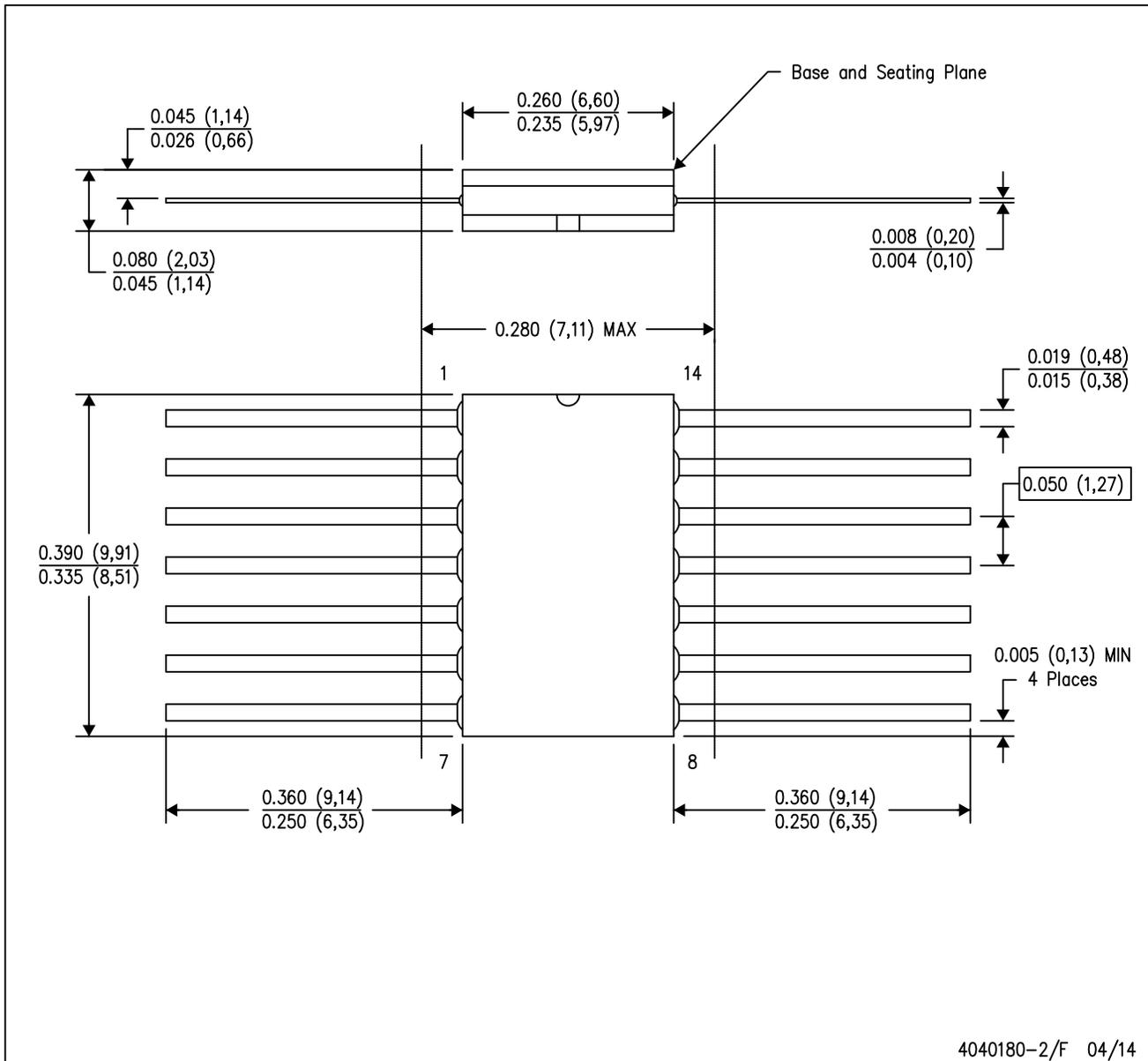
**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-8762401VDA	W	CFP	14	25	506.98	26.16	6220	NA
5962-8762402VDA	W	CFP	14	25	506.98	26.16	6220	NA

W (R-GDFP-F14)

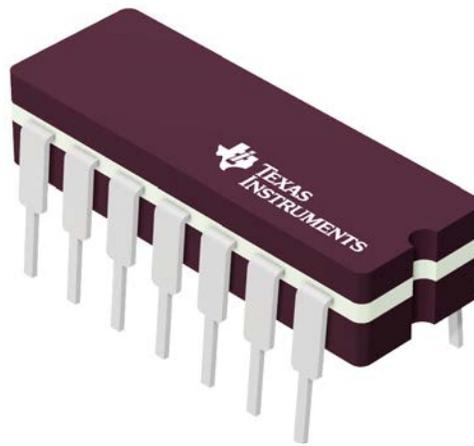
CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14

J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

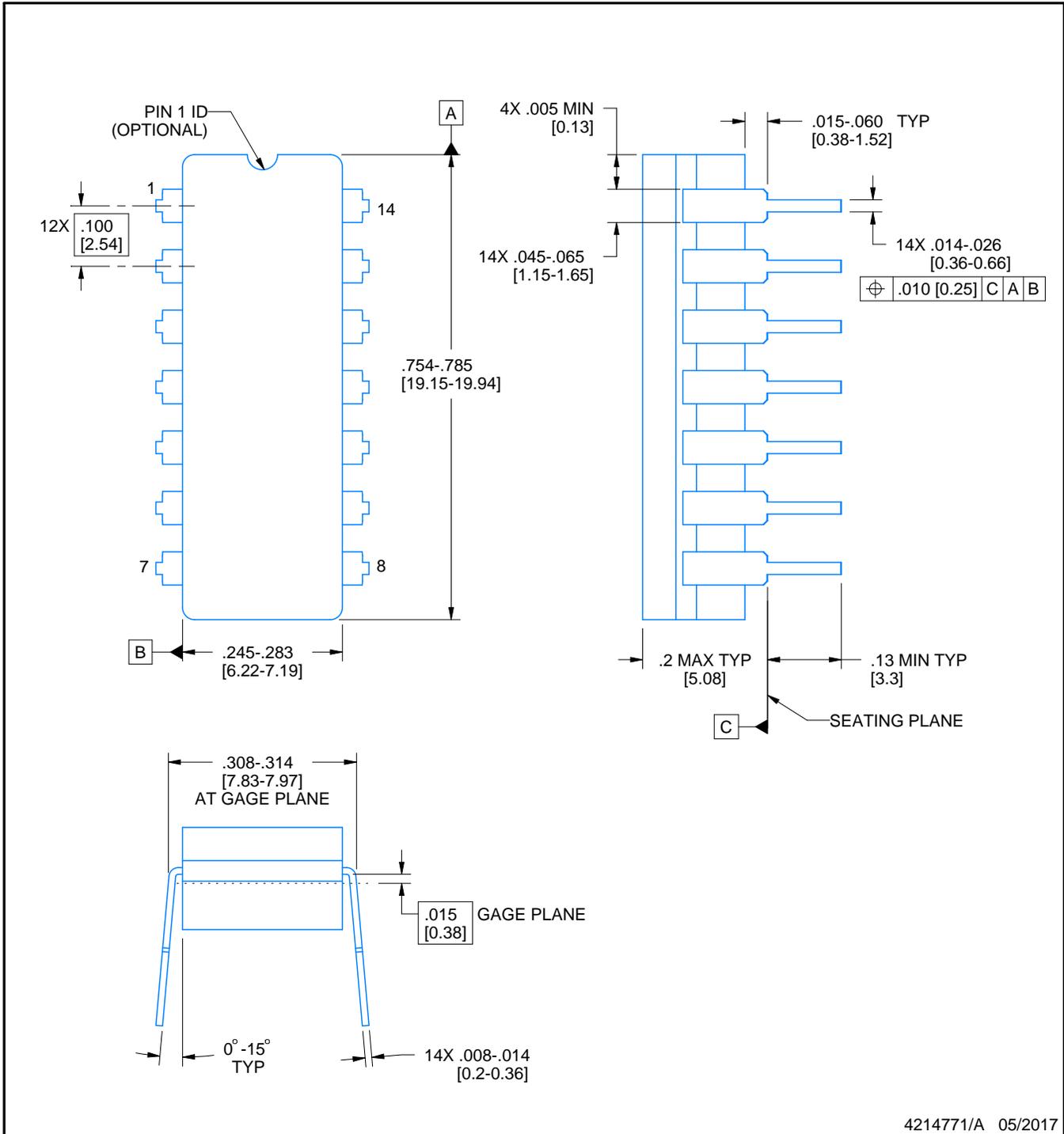
J0014A



# PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



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NOTES:

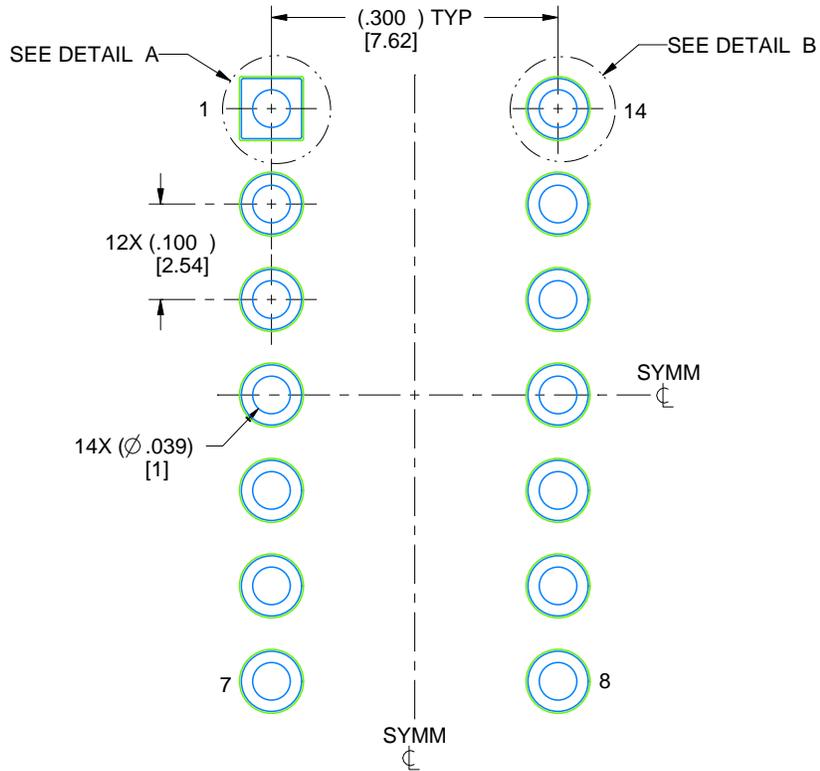
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

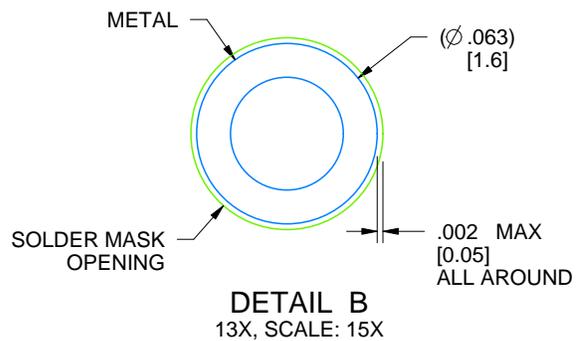
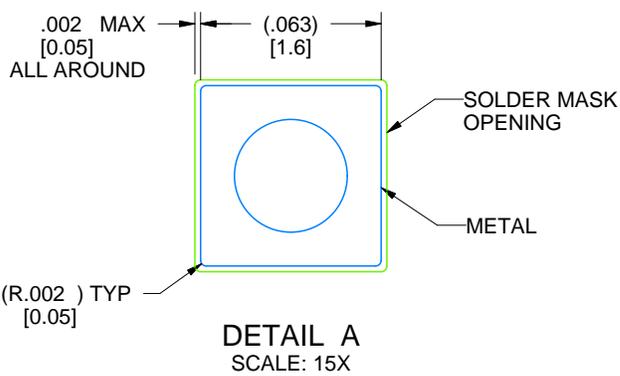
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017

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